

VQ2006 SERIES

Siliconix
incorporated

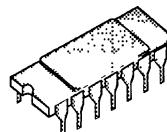
P-Channel Enhancement-Mode MOS Transistor
Arrays

PRODUCT SUMMARY

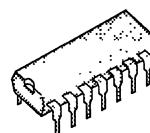
PART NUMBER	$V_{(BR)DSS}$ (V)	$r_{DS(ON)}$ (Ω)	I_D (A)	PACKAGE
VQ2006J	-90	5	-0.41	Plastic
VQ2006P	-90	5	-0.41	Side Braze

Performance Curves: VPDV10 (See Section 7)

14-PIN DIP
SIDE BRAZE

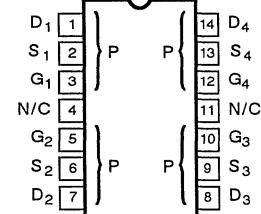


14-PIN PLASTIC



TOP VIEW

Dual-In-Line Package



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	VQ2006J	VQ2006P	UNITS
Drain-Source Voltage	V_{DS}	-90	-90	V
Gate-Source Voltage	V_{GS}	± 30	± 20	
Continuous Drain Current	I_D	-0.41	-0.41	A
		-0.23	-0.23	
Pulsed Drain Current ¹	I_{DM}	± 3	± 3	W
Power Dissipation – Single	P_D	1.3	1.3	
		0.52	0.52	
Power Dissipation – Quad		2	2	
		0.8	0.8	
Operating Junction and Storage Temperature	T_J, T_{stg}	-55 to 150		°C
Lead Temperature (1/16" from case for 10 seconds)	T_L	300		

THERMAL RESISTANCE

THERMAL RESISTANCE	SYMBOL	VQ2006J	VQ2006P	UNITS
Junction-to-Ambient – Single	R_{thJA}	96.2	96.2	°C/W
Junction-to-Ambient – Quad		62.5	62.5	

¹Pulse width limited by maximum junction temperature

ELECTRICAL CHARACTERISTICS ¹			LIMITS			
PARAMETER	SYMBOL	TEST CONDITIONS	TYP ²	VQ2006 ⁴		UNIT
				MIN	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}$, $I_D = -10 \mu\text{A}$	-110	-90		V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = -1 \text{ mA}$	-3.4	-2	-4.5	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$	± 1		± 100	nA
		$V_{GS} = \pm 30 \text{ V}$	$T_J = 125^\circ\text{C}$	± 5	± 500	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -90 \text{ V}$	-0.0005		-10	μA
		$V_{GS} = 0 \text{ V}$	$T_J = 125^\circ\text{C}$	-0.1	-500	
On-State Drain Current ³	$I_{D(\text{ON})}$	$V_{DS} = -10 \text{ V}$, $V_{GS} = -10 \text{ V}$	-2	-1		A
Drain-Source On-Resistance ³	$r_{DS(\text{ON})}$	$V_{GS} = -10 \text{ V}$	2.5		5	Ω
		$I_D = -1 \text{ A}$	$T_J = 125^\circ\text{C}$	4.3	8	
Forward Transconductance ³	g_{FS}	$V_{DS} = -10 \text{ V}$, $I_D = -0.5 \text{ A}$	325	200		mS
Common Source Output Conductance ³	g_{OS}	$V_{DS} = -7.5 \text{ V}$, $I_D = -0.1 \text{ A}$	450			μs
DYNAMIC						
Input Capacitance	C_{iss}	$V_{DS} = -25 \text{ V}$ $V_{GS} = 0 \text{ V}$ $f = 1 \text{ MHz}$	75		150	pF
Output Capacitance	C_{oss}		40		60	
Reverse Transfer Capacitance	C_{rss}		18		25	
SWITCHING						
Turn-On Time	$t_{d(\text{ON})}$	$V_{DD} = -25 \text{ V}$, $R_L = 47 \Omega$ $I_D = -0.5 \text{ A}$, $V_{GEN} = -10 \text{ V}$ $R_G = 25 \Omega$ (Switching time is essentially independent of operating temperature)	11		15	ns
	t_r		30		40	
Turn-Off Time	$t_{d(\text{OFF})}$		20		30	
	t_f		20		30	

- NOTES: 1. $T_A = 25^\circ\text{C}$ unless otherwise noted.
 2. For design aid only, not subject to production testing.
 3. Pulse test; PW = 300 μs , duty cycle $\leq 2\%$.
 4. Data sheet limits have been revised.